

EAST Search History**EAST Search History (Prior Art)**

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EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(Method process procedure) and deposit \$4 near metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 with etch\$4 and slop\$4 near2 sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:33
L2	0	(Method process procedure) and deposit \$4 with metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 with etch\$4 and slop\$4 near2 sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:33

L3	0	(Method process procedure) and deposit \$4 with metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 and etch\$4 and slop\$4 with sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:34
L4	0	(Method process procedure) and deposit \$4 same metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 and etch\$4 and slop\$4 with sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:34
L5	0	(Method process procedure) and deposit \$4 and metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 and etch\$4 and slop\$4 and sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:35

L6	0	(Method process procedure) and deposit \$4 and metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and galvanic and sputter \$4 and etch\$4 and slop\$4 and sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:35
L7	1	(Method process procedure) and deposit \$4 and metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and galvanic and sputter \$4 and etch\$4 and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:36
L8	1	(Method process procedure) and deposit \$4 and metal and substrate and \$5resist and Pattern\$4 and lithograph\$4 and galvanic and sputter \$4 and etch\$4 and (aluminum adj oxide al203 "Al.sub.2 O.sub.3") and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:37

L9	34	(Method process procedure) and deposit \$4 and metal and substrate and \$5resist and Pattern\$4 and lithograph\$4 and galvanic and sputter \$4 and etch\$4 and (aluminum adj oxide al203 "Al.sub.2 O.sub.3")	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:37
L10	1	(Method process procedure) and deposit \$4 near metal and thickness and substrate and \$5resist and Pattern\$4 and lithograph\$4 and negative adj slope and galvanic and sputter \$4 with etch\$4 and slop\$4 near2 sidewall and (aluminum adj oxide al203 "Al.sub.2 O.sub.3" aluminumoxide) and self-aligned	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:38
L11	0	((Method process procedure) and deposit \$4 and metal and substrate and \$5resist and Pattern\$4 and lithograph\$4 and galvanic and sputter \$4 and etch\$4 and (aluminum adj oxide al203 "Al.sub.2 O.sub.3"))).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2009/12/04 15:39

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